

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6220276

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	PEI-LING KAO	05/29/2020
	YOU-TING LIN	05/29/2020
	JIUN-MING KUO	05/29/2020
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
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City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16885871	
CORRESPONDENCE DATA		
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ATTORNEY DOCKET NUMBER:	0941-4374PUS1	
NAME OF SUBMITTER:	LYNN LAM	
SIGNATURE:	/lynn lam/	
DATE SIGNED:	07/27/2020	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS, Pei-Ling KAO, You-Ting LIN and Jiun-Ming KUO
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as
described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR STRUCTURE AND METHOD FOR FORMING THE SAME

Filed: May 28, 2020

Serial No. 16/885,871

Executed on: May 29, 2020

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu
Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous
of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters
Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and
valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have
sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said
Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to
the said invention and application and all future improvements thereon, and in and to any Letters
Patent which may hereafter be granted on the same in the United States, the said interest to be held
and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by
said Assignor had this Assignment and transfer not been made, to the full end and term of any
Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or
in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee,
but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or
applications, execute, verify, acknowledge and deliver all such further papers, including
applications for Letters Patent and for the reissue thereof, and instruments of assignment and
transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or
maintain Letters Patent for said invention and improvement, and to vest title thereto in said
Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)
indicated.

ASSIGNMENT

<u>5/29, 2020</u>	<u>高佩玲</u>
Date	Name: Pei-Ling KAO
<u>5/29, 2020</u>	<u>林育廷</u>
Date	Name: You-Ting LIN
<u>5/29, 2020</u>	<u>郭俊銘</u>
Date	Name: Jiun-Ming KUO